ACMA POT Series

Winding Type Chip Inductor

Size 3225

FEATURKOHEicPerPropert PO:ie 32βBT0.05s Aβ.0.7APPLI 0T(C)T4

Ferrite core wire wound construc on.

High Reliability due to wire wound type construc on.

Small footprint as well as low profile.

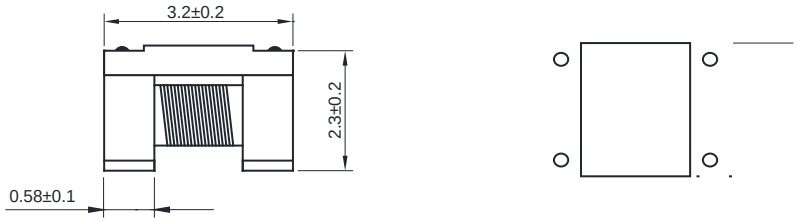
100% Lead(Pb) & Halogen-Free and RoHS compliant.

AEC-Q200 qualified

Opera ng temperature-55~+150℃

Quan ty: 1500pcs

Inductor for use in in-vehicle PoC (Power Over Coax)

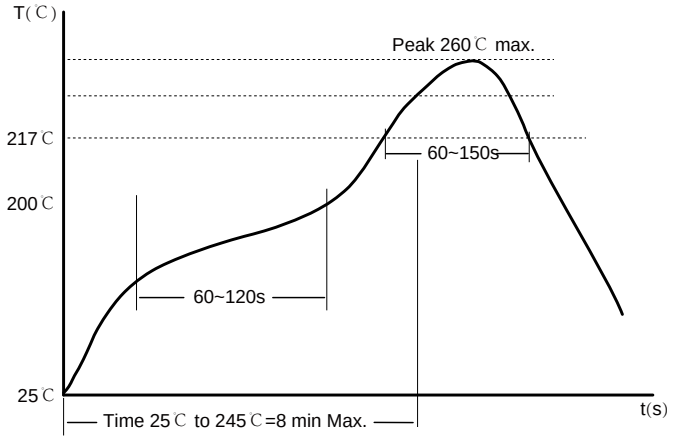


Part No		Tol.	R_{DC} Max. (Ω)		
ACMA3225POT-4R7M	4.7	±20%	0.10	720	1500
ACMA3225POT-100M	10.0	±20%	0.15	450	1300

I_{SAT}: When based on the inductance change rate (30% below the ini al L value)

I_R: When based on the temperature increase (temperature increase of 40°C by self-hea ng)

Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~150 sec.

Max temperature: 260℃.

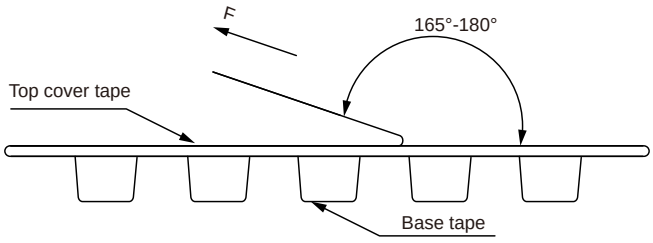
Allowed Reflow time: 3x max.

Packaging Information:

Tape Dimension:

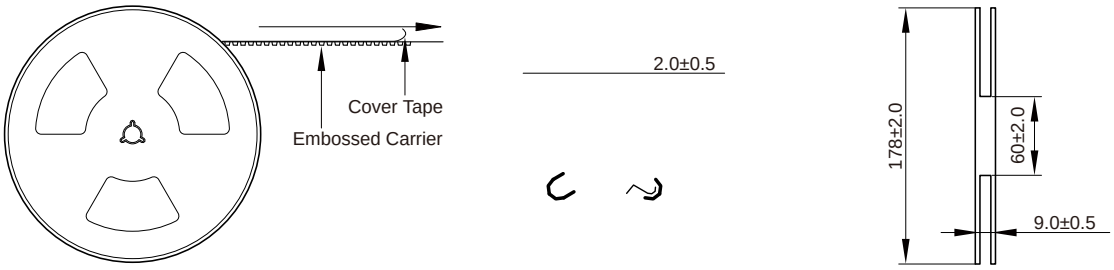
Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
ACMA3225POT	2.70 ± 0.1	3.50 ± 0.1	1.5 ± 0.1	4.0 ± 0.1	4.0 ± 0.1	8.0 ± 0.3	2.75 ± 0.1	1.75 ± 0.1	0.30 ± 0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.14 to 0.78 N

Reel Dimension：[mm]



Cautions and Warnings:

Storage Conditions：

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.